



Welcome to [E-XFL.COM](#)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I ² C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	28KB (16K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 14x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1939-e-ml

PIC16(L)F1938/9

TABLE 1-2: PIC16(L)F1938/9 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RA6/OSC2/CLKOUT/VCAP ⁽²⁾ /SEG1	RA6	TTL	CMOS	General purpose I/O.
	OSC2	—	XTAL	Crystal/Resonator (LP, XT, HS modes).
	CLKOUT	—	CMOS	Fosc/4 output.
	VCAP	Power	Power	Filter capacitor for Voltage Regulator (PIC16F1938/9 only).
	SEG1	—	AN	LCD Analog output.
RA7/OSC1/CLKIN/SEG2	RA7	TTL	CMOS	General purpose I/O.
	OSC1	XTAL	—	Crystal/Resonator (LP, XT, HS modes).
	CLKIN	CMOS	—	External clock input (EC mode).
	SEG2	—	AN	LCD Analog output.
RB0/AN12/CPS0/CCP4/SRI/INT/SEG0	RB0	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN12	AN	—	A/D Channel 12 input.
	CPS0	AN	—	Capacitive sensing input 0.
	CCP4	ST	CMOS	Capture/Compare/PWM4.
	SRI	—	ST	SR Latch input.
	INT	ST	—	External interrupt.
	SEG0	—	AN	LCD analog output.
RB1/AN10/C12IN3-/CPS1/P1C/VLCD1	RB1	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN10	AN	—	A/D Channel 10 input.
	C12IN3-	AN	—	Comparator C1 or C2 negative input.
	CPS1	AN	—	Capacitive sensing input 1.
	P1C	—	CMOS	PWM output.
	VLCD1	AN	—	LCD analog input.
RB2/AN8/CPS2/P1B/VLCD2	RB2	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN8	AN	—	A/D Channel 8 input.
	CPS2	AN	—	Capacitive sensing input 2.
	P1B	—	CMOS	PWM output.
	VLCD2	AN	—	LCD analog input.
RB3/AN9/C12IN2-/CPS3/CCP2 ⁽¹⁾ /P2A ⁽¹⁾ /VLCD3	RB3	TTL	CMOS	General purpose I/O. Individually controlled interrupt-on-change. Individually enabled pull-up.
	AN9	AN	—	A/D Channel 9 input.
	C12IN2-	AN	—	Comparator C1 or C2 negative input.
	CPS3	AN	—	Capacitive sensing input 3.
	CCP2	ST	CMOS	Capture/Compare/PWM2.
	P2A	—	CMOS	PWM output.
	VLCD3	AN	—	LCD analog input.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels XTAL = Crystal
HV = High Voltage I²C™ = Schmitt Trigger input with I²C levels

- Note** 1: Pin function is selectable via the APFCON register.
2: PIC16F1938/9 devices only.
3: PIC16(L)F1938 devices only.
4: PORTD is available on PIC16(L)F1939 devices only.
5: RE<2:0> are available on PIC16(L)F1939 devices only.

PIC16(L)F1938/9

TABLE 1-2: PIC16(L)F1938/9 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RC4/SDI/SDA/T1G ⁽¹⁾ /SEG11	RC4	ST	CMOS	General purpose I/O.
	SDI	ST	—	SPI data input.
	SDA	I ² C	OD	I ² C™ data input/output.
	T1G	ST	—	Timer1 Gate input.
	SEG11	—	AN	LCD Analog output.
RC5/SDO/SEG10	RC5	ST	CMOS	General purpose I/O.
	SDO	—	CMOS	SPI data output.
	SEG10	—	AN	LCD Analog output.
RC6/TX/CK/CCP3/P3A/SEG9	RC6	ST	CMOS	General purpose I/O.
	TX	—	CMOS	USART asynchronous transmit.
	CK	ST	CMOS	USART synchronous clock.
	CCP3	ST	CMOS	Capture/Compare/PWM3.
	P3A	—	CMOS	PWM output.
	SEG9	—	AN	LCD Analog output.
RC7/RX/DT/P3B/SEG8	RC7	ST	CMOS	General purpose I/O.
	RX	ST	—	USART asynchronous input.
	DT	ST	CMOS	USART synchronous data.
	P3B	—	CMOS	PWM output.
	SEG8	—	AN	LCD Analog output.
RD0 ⁽⁴⁾ /CPS8/COM3	RD0	ST	CMOS	General purpose I/O.
	CPS8	AN	—	Capacitive sensing input 8.
	COM3	—	AN	LCD analog output.
RD1 ⁽⁴⁾ /CPS9/CCP4	RD1	ST	CMOS	General purpose I/O.
	CPS9	AN	—	Capacitive sensing input 9.
	CCP4	ST	CMOS	Capture/Compare/PWM4.
RD2 ⁽⁴⁾ /CPS10/P2B	RD2	ST	CMOS	General purpose I/O.
	CPS10	AN	—	Capacitive sensing input 10.
	P2B	—	CMOS	PWM output.
RD3 ⁽⁴⁾ /CPS11/P2C/SEG16	RD3	ST	CMOS	General purpose I/O.
	CPS11	AN	—	Capacitive sensing input 11.
	P2C	—	CMOS	PWM output.
	SEG16	—	AN	LCD analog output.
RD4 ⁽⁴⁾ /CPS12/P2D/SEG17	RD4	ST	CMOS	General purpose I/O.
	CPS12	AN	—	Capacitive sensing input 12.
	P2D	—	CMOS	PWM output.
	SEG17	—	AN	LCD analog output.
RD5 ⁽⁴⁾ /CPS13/P1B/SEG18	RD5	ST	CMOS	General purpose I/O.
	CPS13	AN	—	Capacitive sensing input 13.
	P1D	—	CMOS	PWM output.
	SEG18	—	AN	LCD analog output.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels XTAL = Crystal
HV = High Voltage I²C™ = Schmitt Trigger input with I²C levels

- Note** 1: Pin function is selectable via the APFCON register.
2: PIC16F1938/9 devices only.
3: PIC16(L)F1938 devices only.
4: PORTD is available on PIC16(L)F1939 devices only.
5: RE<2:0> are available on PIC16(L)F1939 devices only.

TABLE 3-10: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

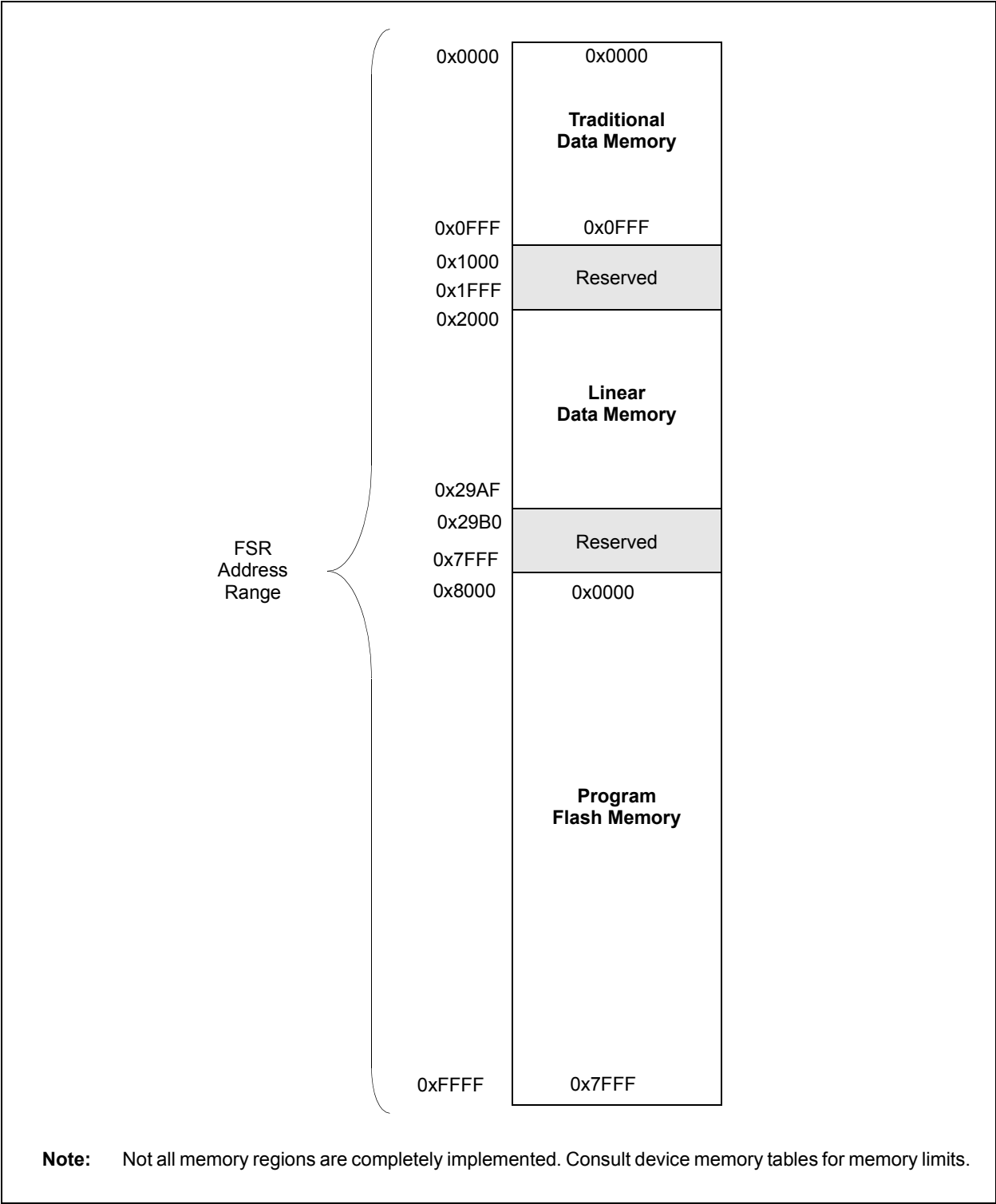
Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 15 (Continued)											
7A6h	LCDDATA6	SEG7 COM2	SEG6 COM2	SEG5 COM2	SEG4 COM2	SEG3 COM2	SEG2 COM2	SEG1 COM2	SEG0 COM2	xxxx xxxx	uuuu uuuu
7A7h	LCDDATA7	SEG15 COM2	SEG14 COM2	SEG13 COM2	SEG12 COM2	SEG11 COM2	SEG10 COM2	SEG9 COM2	SEG8 COM2	xxxx xxxx	uuuu uuuu
7A8h	LCDDATA8 ⁽³⁾	SEG23 COM2	SEG22 COM2	SEG21 COM2	SEG20 COM2	SEG19 COM2	SEG18 COM2	SEG17 COM2	SEG16 COM2	xxxx xxxx	uuuu uuuu
7A9h	LCDDATA9	SEG7 COM3	SEG6 COM3	SEG5 COM3	SEG4 COM3	SEG3 COM3	SEG2 COM3	SEG1 COM3	SEG0 COM3	xxxx xxxx	uuuu uuuu
7AAh	LCDDATA10	SEG15 COM3	SEG14 COM3	SEG13 COM3	SEG12 COM3	SEG11 COM3	SEG10 COM3	SEG9 COM3	SEG8 COM3	xxxx xxxx	uuuu uuuu
7ABh	LCDDATA11 ⁽³⁾	SEG23 COM3	SEG22 COM3	SEG21 COM3	SEG20 COM3	SEG19 COM3	SEG18 COM3	SEG17 COM3	SEG16 COM3	xxxx xxxx	uuuu uuuu
7ACh — 7EFh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved.
Shaded locations are unimplemented, read as '0'.

- Note 1:** The upper byte of the program counter is not directly accessible. PCLATH is a holding register for the PC<14:8>, whose contents are transferred to the upper byte of the program counter.
- 2:** These registers can be addressed from any bank.
- 3:** These registers/bits are not implemented on PIC16(L)F1938 devices, read as '0'.
- 4:** Unimplemented, read as '1'.

PIC16(L)F1938/9

FIGURE 3-8: INDIRECT ADDRESSING



PIC16(L)F1938/9

6.1 Power-on Reset (POR)

The POR circuit holds the device in Reset until VDD has reached an acceptable level for minimum operation. Slow rising VDD, fast operating speeds or analog performance may require greater than minimum VDD. The PWRT, BOR or MCLR features can be used to extend the start-up period until all device operation conditions have been met.

6.1.1 POWER-UP TIMER (PWRT)

The Power-up Timer provides a nominal 64 ms time-out on POR or Brown-out Reset.

The device is held in Reset as long as PWRT is active. The PWRT delay allows additional time for the VDD to rise to an acceptable level. The Power-up Timer is enabled by clearing the PWRTE bit in Configuration Words.

The Power-up Timer starts after the release of the POR and BOR.

For additional information, refer to Application Note AN607, "Power-up Trouble Shooting" (DS00607).

6.2 Brown-Out Reset (BOR)

The BOR circuit holds the device in Reset when VDD reaches a selectable minimum level. Between the POR and BOR, complete voltage range coverage for execution protection can be implemented.

The Brown-out Reset module has four operating modes controlled by the BOREN<1:0> bits in Configuration Words. The four operating modes are:

- BOR is always on
- BOR is off when in Sleep
- BOR is controlled by software
- BOR is always off

Refer to [Table 6-3](#) for more information.

The Brown-out Reset voltage level is selectable by configuring the BORV bit in Configuration Words.

A VDD noise rejection filter prevents the BOR from triggering on small events. If VDD falls below VBOR for a duration greater than parameter TBORDC, the device will reset. See [Figure 6-2](#) for more information.

TABLE 6-1: BOR OPERATING MODES

BOREN<1:0>	SBOREN	Device Mode	BOR Mode	Device Operation upon release of POR	Device Operation upon wake-up from Sleep
11	X	X	Active	Waits for BOR ready ⁽¹⁾	
10	X	Awake	Active	Waits for BOR ready	
		Sleep	Disabled		
01	1	X	Active	Begins immediately	
	0		Disabled	Begins immediately	
00	X	X	Disabled	Begins immediately	

Note 1: In these specific cases, "Release of POR" and "Wake-up from Sleep", there is no delay in start-up. The BOR ready flag, (BORRDY = 1), will be set before the CPU is ready to execute instructions because the BOR circuit is forced on by the BOREN<1:0> bits.

6.2.1 BOR IS ALWAYS ON

When the BOREN bits of Configuration Words are programmed to '11', the BOR is always on. The device start-up will be delayed until the BOR is ready and VDD is higher than the BOR threshold.

BOR protection is active during Sleep. The BOR does not delay wake-up from Sleep.

6.2.2 BOR IS OFF IN SLEEP

When the BOREN bits of Configuration Words are programmed to '10', the BOR is on, except in Sleep. The device start-up will be delayed until the BOR is ready and VDD is higher than the BOR threshold.

BOR protection is not active during Sleep. The device wake-up will be delayed until the BOR is ready.

6.2.3 BOR CONTROLLED BY SOFTWARE

When the BOREN bits of Configuration Words are programmed to '01', the BOR is controlled by the SBOREN bit of the BORCON register. The device start-up is not delayed by the BOR ready condition or the VDD level.

BOR protection begins as soon as the BOR circuit is ready. The status of the BOR circuit is reflected in the BORRDY bit of the BORCON register.

BOR protection is unchanged by Sleep.

PIC16(L)F1938/9

REGISTER 12-16: LATD: PORTD DATA LATCH REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
LATD7	LATD6	LATD5	LATD4	LATD3	LATD2	LATD1	LATD0
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
u = Bit is unchanged x = Bit is unknown -n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set '0' = Bit is cleared

bit 7-0 **LATD<7:0>**: PORTD Output Latch Value bits^(1,2)

Note 1: Writes to PORTD are actually written to corresponding LATD register. Reads from PORTD register is return of actual I/O pin values.

2: PORTD implemented on PIC16(L)F1939 devices only.

REGISTER 12-17: ANSEL: PORTD ANALOG SELECT REGISTER⁽²⁾

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
ANSD7	ANSD6	ANSD5	ANSD4	ANSD3	ANSD2	ANSD1	ANSD0
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
u = Bit is unchanged x = Bit is unknown -n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set '0' = Bit is cleared

bit 7-0 **ANSD<7:0>**: Analog Select between Analog or Digital Function on Pins RD<7:0>, respectively

0 = Digital I/O. Pin is assigned to port or digital special function.

1 = Analog input. Pin is assigned as analog input⁽¹⁾. Digital input buffer disabled.

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

2: ANSEL register is not implemented on the PIC16(L)F1938. Read as '0'.

3: PORTD implemented on PIC16(L)F1939 devices only.

TABLE 12-11: SUMMARY OF REGISTERS ASSOCIATED WITH PORTD⁽¹⁾

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSEL	ANSD7	ANSD6	ANSD5	ANSD4	ANSD3	ANSD2	ANSD1	ANSD0	138
CCPxCON	PxM<1:0>		DCxB<1:0>		CCPxM<3:0>				228
CPSCON0	CPSON	CPSRM	—	—	CPSRNG<1:0>		CPSOUT	T0XCS	321
CPSCON1	—	—	—	—	CPSCH<3:0>				322
LATD	LATD7	LATD6	LATD5	LATD4	LATD3	LATD2	LATD1	LATD0	138
LCDCON	LCDEN	SLPEN	WERR	—	CS<1:0>		LMUX<1:0>		327
LCDSE2	SE23	SE22	SE21	SE20	SE19	SE18	SE17	SE16	331
PORTD	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	137
TRISD	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	137

Legend: x = unknown, u = unchanged, — = unimplemented locations read as '0'. Shaded cells are not used by PORTD.

Note 1: These registers are not implemented on the PIC16(L)F1938 devices, read as '0'.

REGISTER 12-20: LATE: PORTE DATA LATCH REGISTER

U-0	U-0	U-0	U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u
—	—	—	—	—	LATE2 ⁽²⁾	LATE1 ⁽²⁾	LATE0 ⁽²⁾
bit 7							bit 0

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-4 **Unimplemented:** Read as '0'

bit 3-0 **LATE<3:0>:** PORTE Output Latch Value bits⁽¹⁾

Note 1: Writes to PORTE are actually written to corresponding LATE register. Reads from PORTE register is return of actual I/O pin values.

2: LATE register is not implemented on the PIC16(L)F1938. Read as '0'

REGISTER 12-21: ANSELE: PORTE ANALOG SELECT REGISTER

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1
—	—	—	—	—	ANSE2 ⁽²⁾	ANSE1 ⁽²⁾	ANSE0 ⁽²⁾
bit 7							bit 0

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-3 **Unimplemented:** Read as '0'

bit 2-0 **ANSE<2:0>:** Analog Select between Analog or Digital Function on Pins RE<2:0>, respectively
 0 = Digital I/O. Pin is assigned to port or digital special function.
 1 = Analog input. Pin is assigned as analog input⁽¹⁾. Digital input buffer disabled.

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

2: ANSELE register is not implemented on the PIC16(L)F1938. Read as '0'

15.2.6 A/D CONVERSION PROCEDURE

This is an example procedure for using the ADC to perform an Analog-to-Digital conversion:

1. Configure Port:
 - Disable pin output driver (Refer to the TRIS register)
 - Configure pin as analog (Refer to the ANSEL register)
2. Configure the ADC module:
 - Select ADC conversion clock
 - Configure voltage reference
 - Select ADC input channel
 - Turn on ADC module
3. Configure ADC interrupt (optional):
 - Clear ADC interrupt flag
 - Enable ADC interrupt
 - Enable peripheral interrupt
 - Enable global interrupt⁽¹⁾
4. Wait the required acquisition time⁽²⁾.
5. Start conversion by setting the GO/DONE bit.
6. Wait for ADC conversion to complete by one of the following:
 - Polling the GO/DONE bit
 - Waiting for the ADC interrupt (interrupts enabled)
7. Read ADC Result.
8. Clear the ADC interrupt flag (required if interrupt is enabled).

Note 1: The global interrupt can be disabled if the user is attempting to wake-up from Sleep and resume in-line code execution.

2: Refer to [Section 15.4 “A/D Acquisition Requirements”](#).

EXAMPLE 15-1: A/D CONVERSION

```
;This code block configures the ADC
;for polling, Vdd and Vss references, Frc
;clock and AN0 input.
;
;Conversion start & polling for completion
; are included.
;
BANKSEL    ADCON1    ;
MOVLW      B'11110000' ;Right justify, Frc
                                ;clock
MOVWF      ADCON1    ;Vdd and Vss Vref
BANKSEL    TRISA      ;
BSF         TRISA,0    ;Set RA0 to input
BANKSEL    ANSEL      ;
BSF         ANSEL,0    ;Set RA0 to analog
BANKSEL    ADCON0     ;
MOVLW      B'00000001' ;Select channel AN0
MOVWF      ADCON0     ;Turn ADC On
CALL       SampleTime ;Acquisition delay
BSF         ADCON0,ADGO ;Start conversion
BTFSC      ADCON0,ADGO ;Is conversion done?
GOTO       $-1        ;No, test again
BANKSEL    ADRESH     ;
MOVF       ADRESH,W    ;Read upper 2 bits
MOVWF      RESULTHI    ;store in GPR space
BANKSEL    ADRESL     ;
MOVF       ADRESL,W    ;Read lower 8 bits
MOVWF      RESULTLO    ;Store in GPR space
```

TABLE 19-1: SRCLK FREQUENCY TABLE

SRCLK	Divider	Fosc = 32 MHz	Fosc = 20 MHz	Fosc = 16 MHz	Fosc = 4 MHz	Fosc = 1 MHz
111	512	62.5 kHz	39.0 kHz	31.3 kHz	7.81 kHz	1.95 kHz
110	256	125 kHz	78.1 kHz	62.5 kHz	15.6 kHz	3.90 kHz
101	128	250 kHz	156 kHz	125 kHz	31.25 kHz	7.81 kHz
100	64	500 kHz	313 kHz	250 kHz	62.5 kHz	15.6 kHz
011	32	1 MHz	625 kHz	500 kHz	125 kHz	31.3 kHz
010	16	2 MHz	1.25 MHz	1 MHz	250 kHz	62.5 kHz
001	8	4 MHz	2.5 MHz	2 MHz	500 kHz	125 kHz
000	4	8 MHz	5 MHz	4 MHz	1 MHz	250 kHz

PIC16(L)F1938/9

The I²C interface supports the following modes and features:

- Master mode
- Slave mode
- Byte NACKing (Slave mode)
- Limited Multi-master support
- 7-bit and 10-bit addressing
- Start and Stop interrupts
- Interrupt masking
- Clock stretching
- Bus collision detection
- General call address matching
- Address masking
- Address Hold and Data Hold modes
- Selectable SDA hold times

Figure 24-2 is a block diagram of the I²C Interface module in Master mode. Figure 24-3 is a diagram of the I²C Interface module in Slave mode.

FIGURE 24-2: MSSP BLOCK DIAGRAM (I²C™ MASTER MODE)

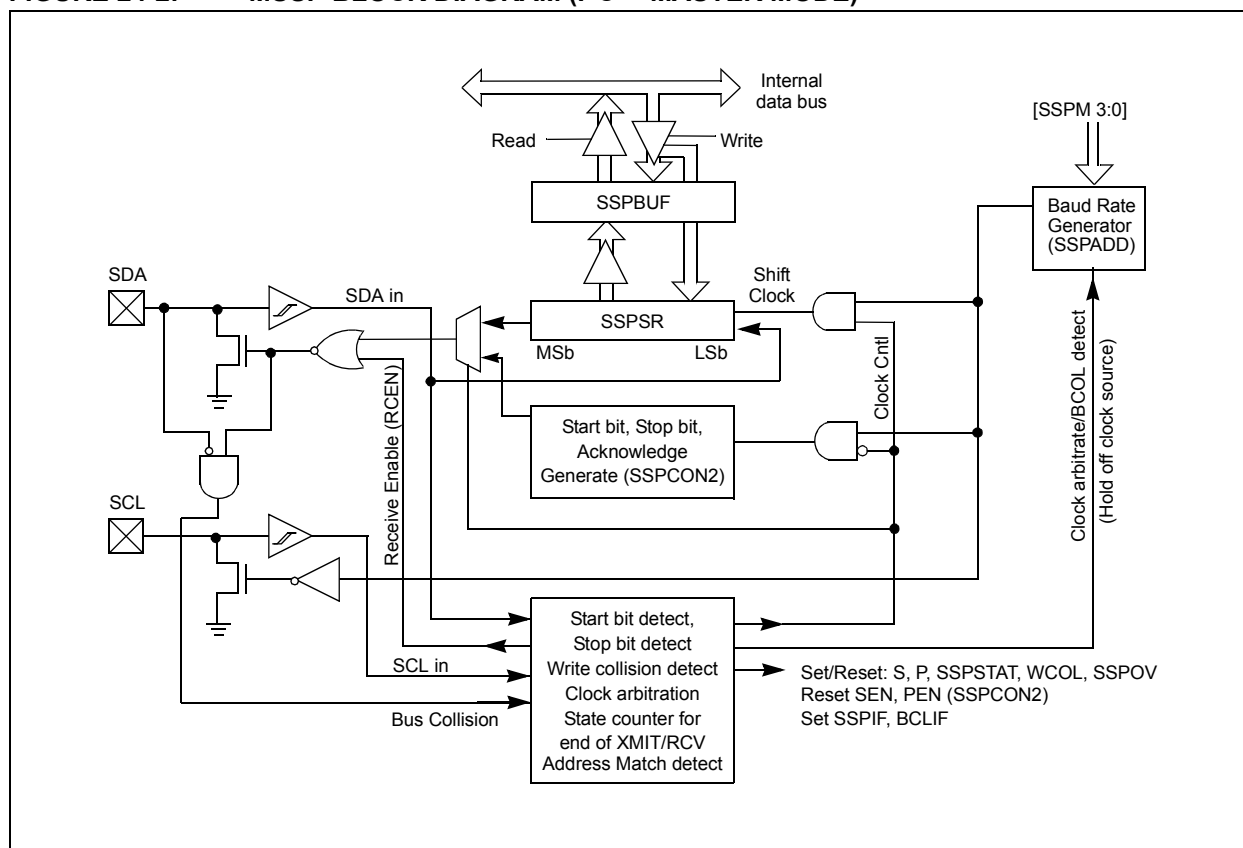
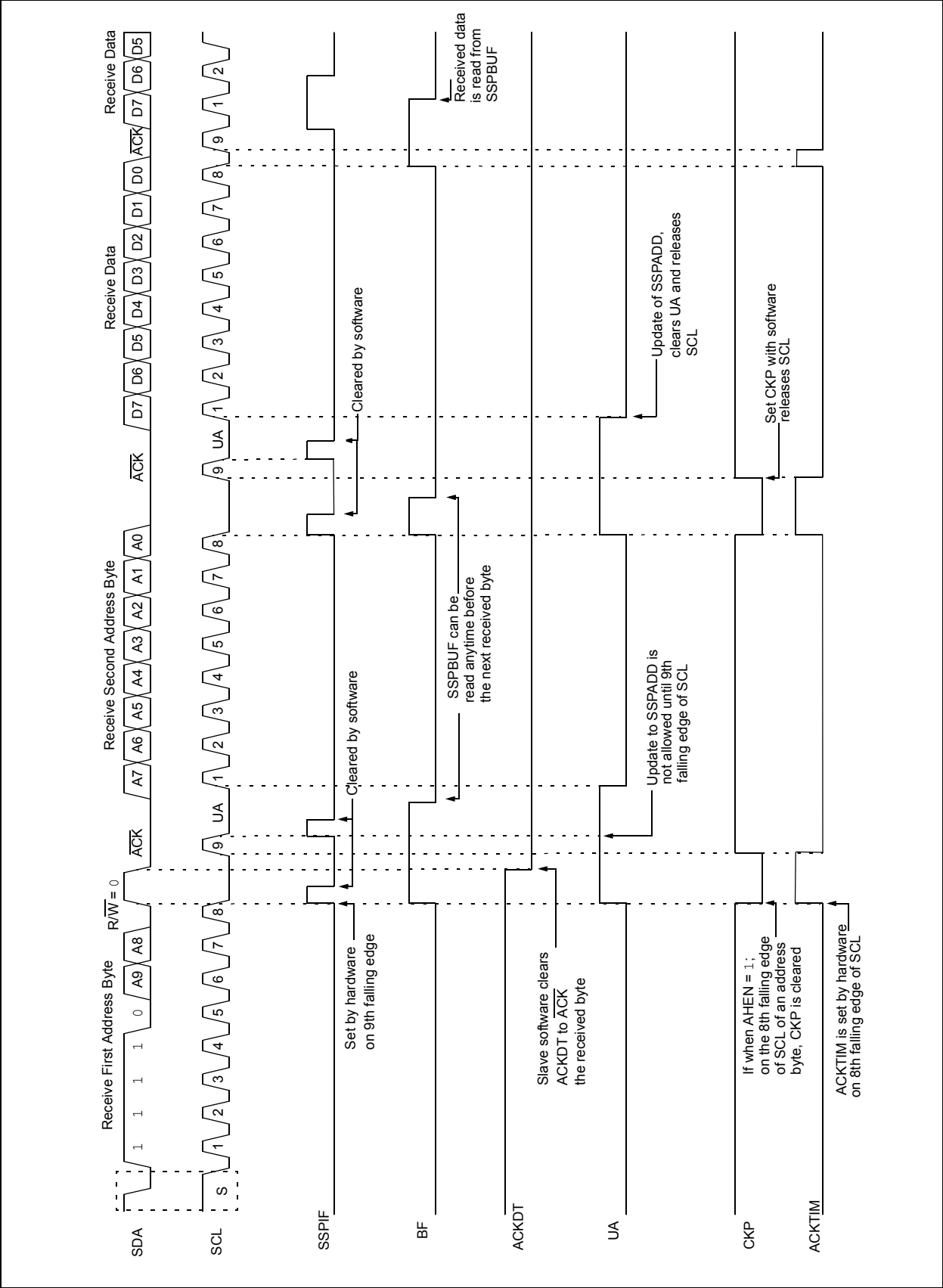


FIGURE 24-21: I²C SLAVE, 10-BIT ADDRESS, RECEPTION (SEN = 0, AHEN = 1, DHEN = 0)



PIC16(L)F1938/9

24.6.13.1 Bus Collision During a Start Condition

During a Start condition, a bus collision occurs if:

- SDA or SCL are sampled low at the beginning of the Start condition (Figure 24-33).
- SCL is sampled low before SDA is asserted low (Figure 24-34).

During a Start condition, both the SDA and the SCL pins are monitored.

If the SDA pin is already low, or the SCL pin is already low, then all of the following occur:

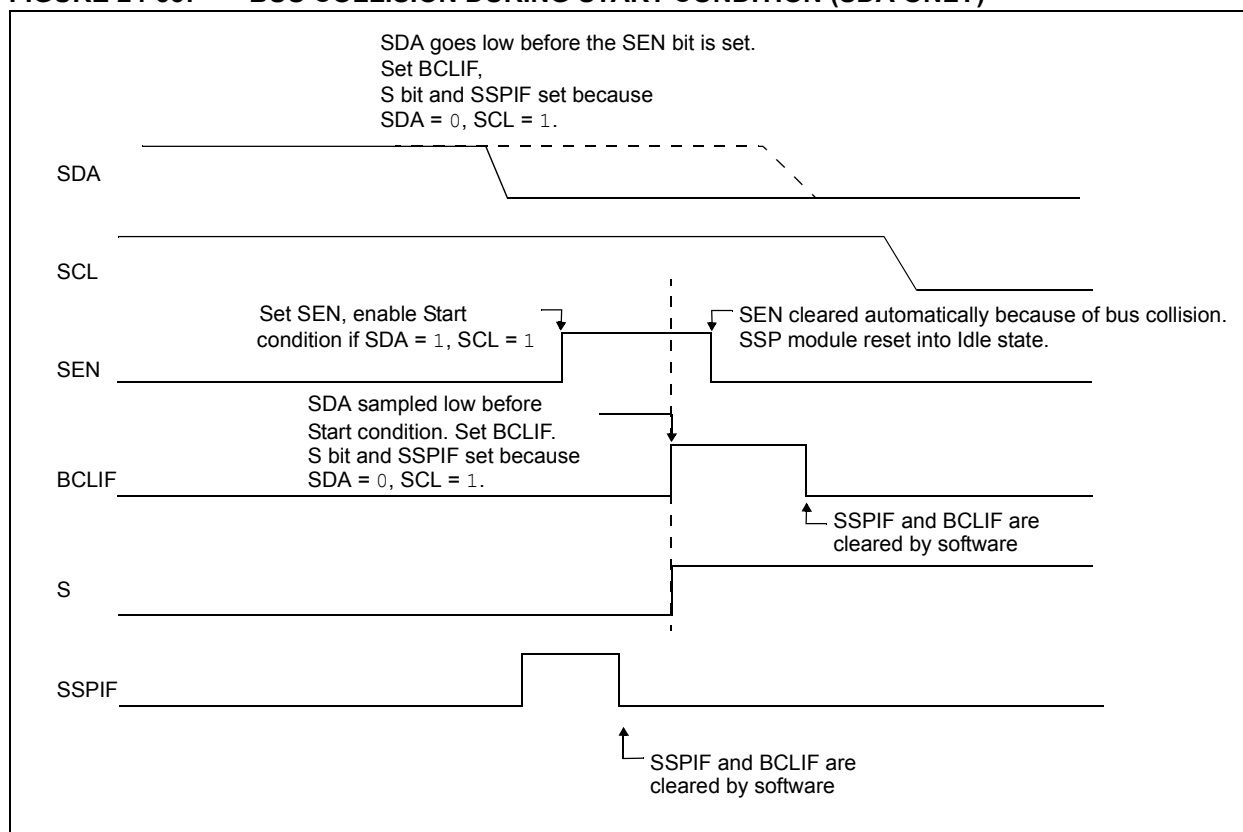
- the Start condition is aborted,
- the BCLIF flag is set and
- the MSSP module is reset to its Idle state (Figure 24-33).

The Start condition begins with the SDA and SCL pins deasserted. When the SDA pin is sampled high, the Baud Rate Generator is loaded and counts down. If the SCL pin is sampled low while SDA is high, a bus collision occurs because it is assumed that another master is attempting to drive a data '1' during the Start condition.

If the SDA pin is sampled low during this count, the BRG is reset and the SDA line is asserted early (Figure 24-35). If, however, a '1' is sampled on the SDA pin, the SDA pin is asserted low at the end of the BRG count. The Baud Rate Generator is then reloaded and counts down to zero; if the SCL pin is sampled as '0' during this time, a bus collision does not occur. At the end of the BRG count, the SCL pin is asserted low.

Note: The reason that bus collision is not a factor during a Start condition is that no two bus masters can assert a Start condition at the exact same time. Therefore, one master will always assert SDA before the other. This condition does not cause a bus collision because the two masters must be allowed to arbitrate the first address following the Start condition. If the address is the same, arbitration must be allowed to continue into the data portion, Repeated Start or Stop conditions.

FIGURE 24-33: BUS COLLISION DURING START CONDITION (SDA ONLY)



27.5 LCD Bias Internal Reference Ladder

The internal reference ladder can be used to divide the LCD bias voltage two or three equally spaced voltages that will be supplied to the LCD segment pins. To create this, the reference ladder consists of three matched resistors. Refer to [Figure 27-3](#).

27.5.1 BIAS MODE INTERACTION

When in 1/2 Bias mode (BIASMD = 1), then the middle resistor of the ladder is shorted out so that only two voltages are generated. The current consumption of the ladder is higher in this mode, with the one resistor removed.

TABLE 27-3: LCD INTERNAL LADDER POWER MODES (1/3 BIAS)

Power Mode	Nominal Resistance of Entire Ladder	Nominal I _{DD}
Low	3 Mohm	1 μ A
Medium	300 kohm	10 μ A
High	30 kohm	100 μ A

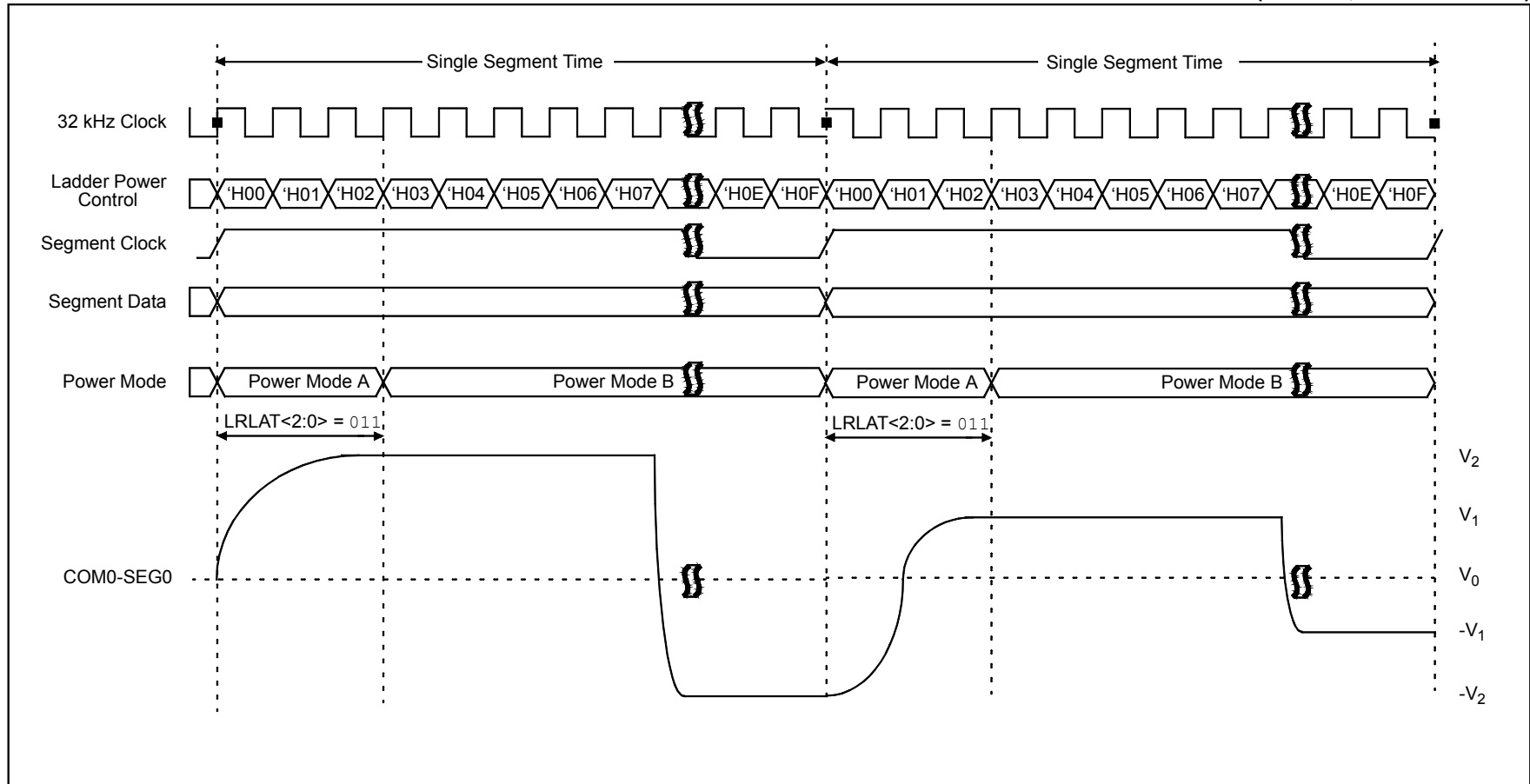
27.5.2 POWER MODES

The internal reference ladder may be operated in one of three power modes. This allows the user to trade off LCD contrast for power in the specific application. The larger the LCD glass, the more capacitance is present on a physical LCD segment, requiring more current to maintain the same contrast level.

Three different power modes are available, LP, MP and HP. The internal reference ladder can also be turned off for applications that wish to provide an external ladder or to minimize power consumption. Disabling the internal reference ladder results in all of the ladders being disconnected, allowing external voltages to be supplied.

Whenever the LCD module is inactive (LCDA = 0), the internal reference ladder will be turned off.

FIGURE 27-5: LCD INTERNAL REFERENCE LADDER POWER MODE SWITCHING DIAGRAM – TYPE A WAVEFORM (1/2 MUX, 1/2 BIAS DRIVE)



29.2 Instruction Descriptions

ADDFSR Add Literal to FSRn

Syntax:	[<i>label</i>] ADDFSR FSRn, k
Operands:	$-32 \leq k \leq 31$ $n \in [0, 1]$
Operation:	$FSR(n) + k \rightarrow FSR(n)$
Status Affected:	None
Description:	The signed 6-bit literal 'k' is added to the contents of the FSRnH:FSRnL register pair. FSRn is limited to the range 0000h - FFFFh. Moving beyond these bounds will cause the FSR to wrap-around.

ANDLW AND literal with W

Syntax:	[<i>label</i>] ANDLW k
Operands:	$0 \leq k \leq 255$
Operation:	$(W) .AND. (k) \rightarrow (W)$
Status Affected:	Z
Description:	The contents of W register are AND'ed with the 8-bit literal 'k'. The result is placed in the W register.

ADDLW Add literal and W

Syntax:	[<i>label</i>] ADDLW k
Operands:	$0 \leq k \leq 255$
Operation:	$(W) + k \rightarrow (W)$
Status Affected:	C, DC, Z
Description:	The contents of the W register are added to the 8-bit literal 'k' and the result is placed in the W register.

ANDWF AND W with f

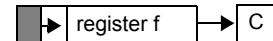
Syntax:	[<i>label</i>] ANDWF f,d
Operands:	$0 \leq f \leq 127$ $d \in [0, 1]$
Operation:	$(W) .AND. (f) \rightarrow (\text{destination})$
Status Affected:	Z
Description:	AND the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

ADDWF Add W and f

Syntax:	[<i>label</i>] ADDWF f,d
Operands:	$0 \leq f \leq 127$ $d \in [0, 1]$
Operation:	$(W) + (f) \rightarrow (\text{destination})$
Status Affected:	C, DC, Z
Description:	Add the contents of the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

ASRF Arithmetic Right Shift

Syntax:	[<i>label</i>] ASRF f {,d}
Operands:	$0 \leq f \leq 127$ $d \in [0, 1]$
Operation:	$(f<7>) \rightarrow \text{dest}<7>$ $(f<7:1>) \rightarrow \text{dest}<6:0>$, $(f<0>) \rightarrow C$,
Status Affected:	C, Z
Description:	The contents of register 'f' are shifted one bit to the right through the Carry flag. The MSb remains unchanged. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is stored back in register 'f'.



ADDWFC ADD W and CARRY bit to f

Syntax:	[<i>label</i>] ADDWFC f {,d}
Operands:	$0 \leq f \leq 127$ $d \in [0, 1]$
Operation:	$(W) + (f) + (C) \rightarrow \text{dest}$
Status Affected:	C, DC, Z
Description:	Add W, the Carry flag and data memory location 'f'. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed in data memory location 'f'.

PIC16(L)F1938/9

DECFSZ Decrement f, Skip if 0

Syntax: [*label*] DECFSZ f,d

Operands: $0 \leq f \leq 127$
 $d \in [0,1]$

Operation: $(f) - 1 \rightarrow (\text{destination})$;
 skip if result = 0

Status Affected: None

Description: The contents of register 'f' are decremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.
 If the result is '1', the next instruction is executed. If the result is '0', then a NOP is executed instead, making it a 2-cycle instruction.

INCFSZ Increment f, Skip if 0

Syntax: [*label*] INCFSZ f,d

Operands: $0 \leq f \leq 127$
 $d \in [0,1]$

Operation: $(f) + 1 \rightarrow (\text{destination})$,
 skip if result = 0

Status Affected: None

Description: The contents of register 'f' are incremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.
 If the result is '1', the next instruction is executed. If the result is '0', a NOP is executed instead, making it a 2-cycle instruction.

GOTO Unconditional Branch

Syntax: [*label*] GOTO k

Operands: $0 \leq k \leq 2047$

Operation: $k \rightarrow PC<10:0>$
 $PCLATH<6:3> \rightarrow PC<14:11>$

Status Affected: None

Description: GOTO is an unconditional branch. The eleven-bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. GOTO is a 2-cycle instruction.

IORLW Inclusive OR literal with W

Syntax: [*label*] IORLW k

Operands: $0 \leq k \leq 255$

Operation: $(W) .OR. k \rightarrow (W)$

Status Affected: Z

Description: The contents of the W register are OR'ed with the 8-bit literal 'k'. The result is placed in the W register.

INCF Increment f

Syntax: [*label*] INCF f,d

Operands: $0 \leq f \leq 127$
 $d \in [0,1]$

Operation: $(f) + 1 \rightarrow (\text{destination})$

Status Affected: Z

Description: The contents of register 'f' are incremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.

IORWF Inclusive OR W with f

Syntax: [*label*] IORWF f,d

Operands: $0 \leq f \leq 127$
 $d \in [0,1]$

Operation: $(W) .OR. (f) \rightarrow (\text{destination})$

Status Affected: Z

Description: Inclusive OR the W register with register 'f'. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.

PIC16(L)F1938/9

TABLE 30-4: CLKOUT AND I/O TIMING PARAMETERS

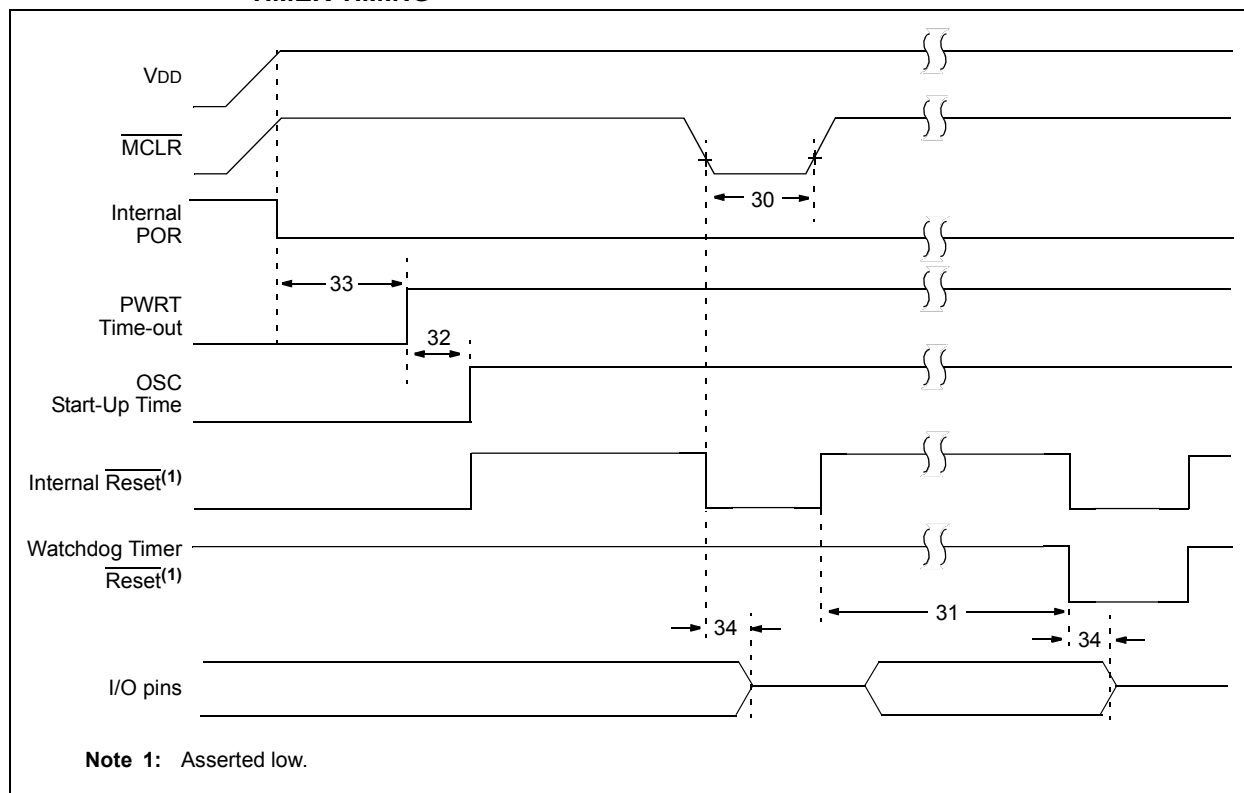
Standard Operating Conditions (unless otherwise stated) Operating Temperature $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$							
Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
OS11	TosH2ckL	Fosc↑ to CLKOUT↓ ⁽¹⁾	—	—	70	ns	VDD = 3.3-5.0V
OS12	TosH2ckH	Fosc↑ to CLKOUT↑ ⁽¹⁾	—	—	72	ns	VDD = 3.3-5.0V
OS13	TckL2ioV	CLKOUT↓ to Port out valid ⁽¹⁾	—	—	20	ns	
OS14	TioV2ckH	Port input valid before CLKOUT↑ ⁽¹⁾	Tosc + 200 ns	—	—	ns	
OS15	TosH2ioV	Fosc↑ (Q1 cycle) to Port out valid	—	50	70*	ns	VDD = 3.3-5.0V
OS16	TosH2ioI	Fosc↑ (Q2 cycle) to Port input invalid (I/O in hold time)	50	—	—	ns	VDD = 3.3-5.0V
OS17	TioV2osH	Port input valid to Fosc↑ (Q2 cycle) (I/O in setup time)	20	—	—	ns	
OS18	TioR	Port output rise time	—	40 15	72 32	ns	VDD = 1.8V VDD = 3.3-5.0V
OS19	TioF	Port output fall time	—	28 15	55 30	ns	VDD = 1.8V VDD = 3.3-5.0V
OS20*	Tinp	INT pin input high or low time	25	—	—	ns	
OS21*	Tioc	Interrupt-on-change new input level time	25	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated.

Note 1: Measurements are taken in RC mode where CLKOUT output is 4 x Tosc.

FIGURE 30-8: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



PIC16(L)F1938/9

TABLE 30-16: I²C™ BUS DATA REQUIREMENTS

Param. No.	Symbol	Characteristic		Min.	Max.	Units	Conditions
SP100*	THIGH	Clock high time	100 kHz mode	4.0	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	μs	Device must operate at a minimum of 10 MHz
			SSP module	1.5Tcy	—		
SP101*	TLOW	Clock low time	100 kHz mode	4.7	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	μs	Device must operate at a minimum of 10 MHz
			SSP module	1.5Tcy	—		
SP102*	TR	SDA and SCL rise time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
SP103*	TF	SDA and SCL fall time	100 kHz mode	—	250	ns	
			400 kHz mode	20 + 0.1Cb	250	ns	Cb is specified to be from 10-400 pF
SP106*	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
SP107*	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	(Note 2)
			400 kHz mode	100	—	ns	
SP109*	TAA	Output valid from clock	100 kHz mode	—	3500	ns	(Note 1)
			400 kHz mode	—	—	ns	
SP110*	TBUF	Bus free time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
SP111	Cb	Bus capacitive loading		—	400	pF	

* These parameters are characterized but not tested.

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of Start or Stop conditions.

2: A Fast mode (400 kHz) I²C™ bus device can be used in a Standard mode (100 kHz) I²C bus system, but the requirement TSU:DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the low period of the SCL signal. If such a device does stretch the low period of the SCL signal, it must output the next data bit to the SDA line TR max. + TSU:DAT = 1000 + 250 = 1250 ns (according to the Standard mode I²C bus specification), before the SCL line is released.

PIC16(L)F1938/9

FIGURE 31-17: I_{DD} TYPICAL, EXTERNAL CLOCK (ECH), HIGH-POWER MODE, PIC16F1938/9 ONLY

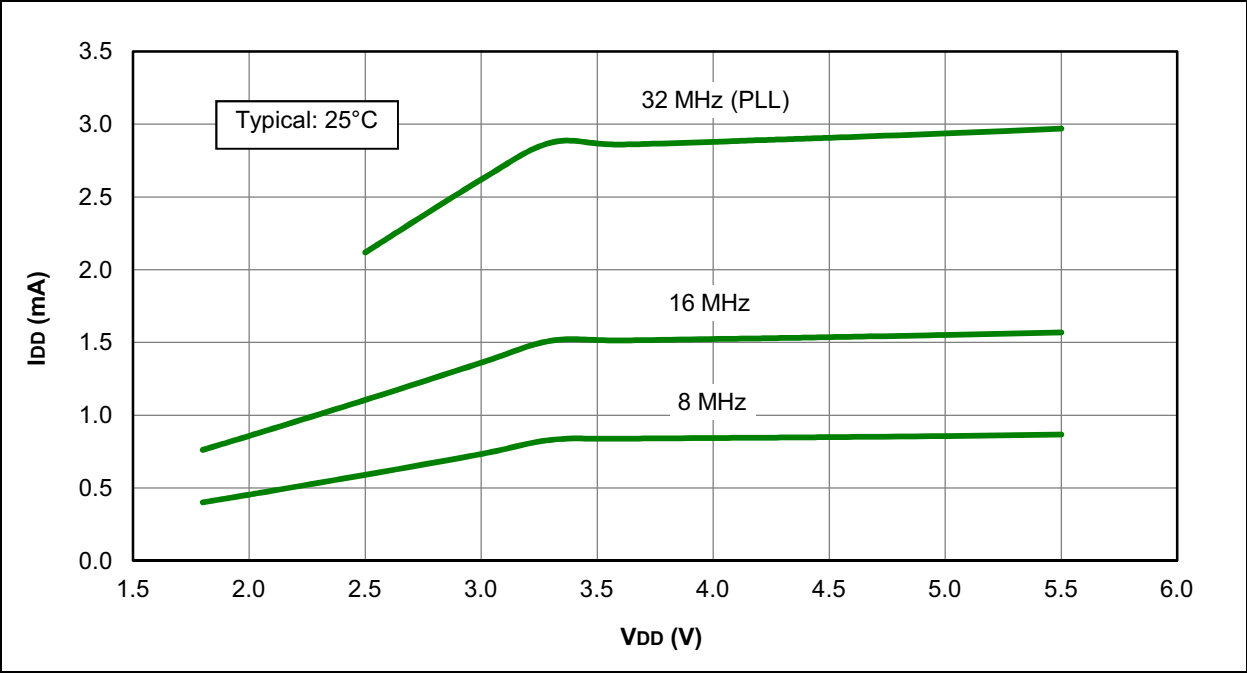
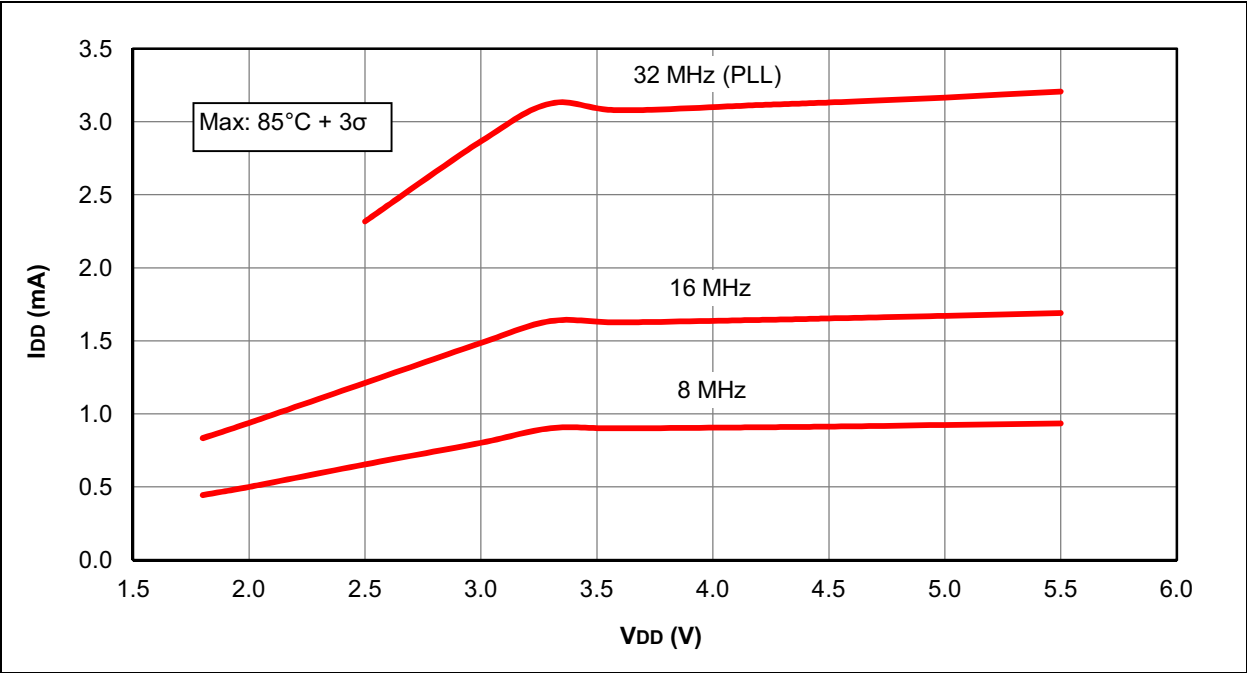


FIGURE 31-18: I_{DD} MAXIMUM, EXTERNAL CLOCK (ECH), HIGH-POWER MODE, PIC16F1938/9 ONLY



PIC16(L)F1938/9

FIGURE 31-49: I_{PD}, COMPARATOR, NORMAL-POWER MODE, (C_xSP = 1), PIC16LF1938/9 ONLY

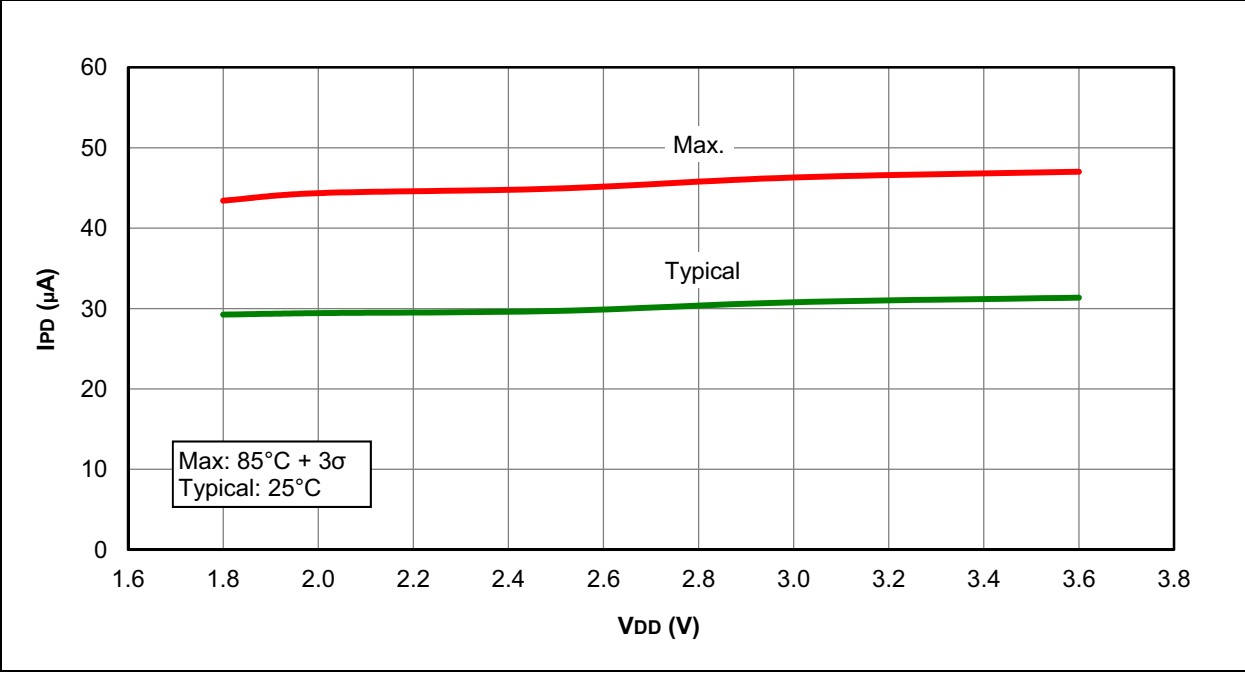


FIGURE 31-50: I_{PD}, COMPARATOR, NORMAL-POWER MODE, (C_xSP = 1), PIC16F1938/9 ONLY

